TPS650350-Q1 汽车摄像头 PMIC

1 特性

- 符合汽车应用要求
- 符合 AEC-Q100 1 级标准
  - –40°C 至 125°C 环境工作温度范围
- 三个降压转换器：
  - BUCK1 V_{IN} 范围为 4.0V 至 18.3V
  - BUCK1 V_{OUT} 范围为 2.5V 至 4.0V
  - BUCK1 输出电流高达 1500mA
  - BUCK2 和 BUCK3 V_{IN} 范围为 2.5 V 至 5.5V
  - BUCK2 和 BUCK3 V_{OUT} 范围为 0.9V 至 1.9V
  - BUCK2 and BUCK3 输出电流高达 1200mA
  - 用于降低 EMI 的扩频时钟 (SSC) 发生器
  - 2.3MHz 强制固定开关频率 PWM 模式工作
- 一个低压降 (LDO) 稳压器：
  - V_{IN} 范围为 2.5 V 至 5.5V
  - V_{OUT} 范围为 1.8V 至 3.3V
  - 低噪声和高 PSRR
  - 可通过 I^2C 调节的输出电压
  - 高达 300mA 的输出电流
- 具有可湿性侧面的 3.0mm × 3.5mm 22 引脚 WQFN 封装

2 应用

- 汽车摄像头模块
  - 环视摄像头模块
  - 后视摄像头模块
  - 驾驶员监控摄像头模块
  - 同轴电缆供电 (POC) 摄像头模块
  - 电子视镜摄像头模块
  - 前视摄像头模块

3 说明

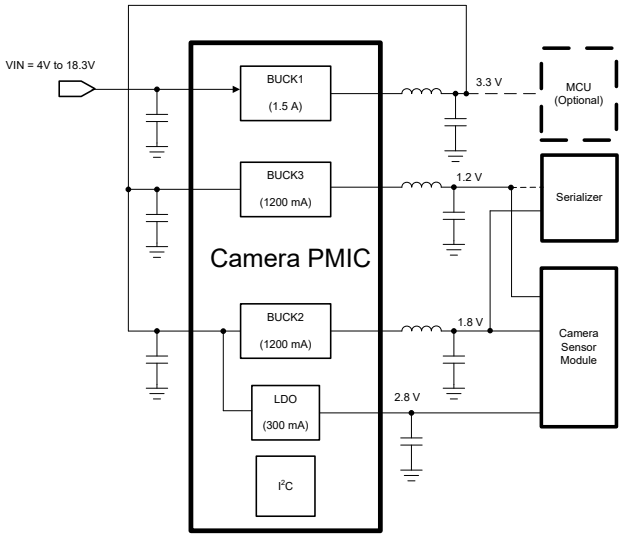
TPS650350-Q1 器件是一种高度集成的电源管理 IC，可适用于汽车摄像头模块。此器件结合了三个降压转换器和一个低压降 (LDO) 稳压器。降压通道 1 降压转换器的输入电压范围高达 18.3V，用于连接到同轴电缆 (PoC)。所有转换器都在强制固定频率 PWM 模式下工作。LDO 可提供 300mA 电流，并可在 2.5 V 至 5.5V 的输入电压范围内正常运行。降压转换器和 LDO 具有独立的电压输入，可实现最大的设计和排序灵活性。

TPS650350-Q1 采用 22 引脚 WQFN 封装 (3.0mm × 3.5mm)。

器件信息

器件型号	封装(1)	封装尺寸（标称值）
TPS650350-Q1	WQFN (22)	3.00mm × 3.50 mm

(1) 如需了解所有可用封装，请参阅数据表末尾的可订购产品附录。



TPS650350-Q1 应用电路

本文档旨在为方便起见，提供有关 TI 产品中文版本的信息，以确认产品的概要。有关适用的官方英文版本的最新信息，请访问 www.ti.com，其内容始终优先。TI 不保证翻译的准确性和有效性。在实际设计之前，请务必参考最新版本的英文版本。

Table of Contents

1 特性.....1
2 应用.....1
3 说明.....1
4 Revision History.....2
5 Device and Documentation Support.....3
5.1 Device Support.....3
5.2 接收文档更新通知.....3
5.3 支持资源.....3
5.4 Trademarks.....3
5.5 静电放电警告.....3
5.6 术语表.....3
6 Mechanical, Packaging, and Orderable Information.....3

4 Revision History

注：以前版本的页码可能与当前版本的页码不同

Changes from Revision * (November 2022) to Revision A (May 2023)	Page
• 将器件状态从“预告信息”更改为“量产数据”	1

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5 Device and Documentation Support

5.1 Device Support

5.1.1 第三方产品免责声明

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5.3 支持资源

TI E2E™ 支持论坛是工程师的重要参考资料，可直接从专家获得快速、经过验证的解答和设计帮助。搜索现有解答或提出自己的问题可获得所需的快速设计帮助。

链接的内容由各个贡献者“按原样”提供。这些内容并不构成 TI 技术规范，并且不一定反映 TI 的观点；请参阅 TI 的《使用条款》。

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5.5 静电放电警告

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ESD 的损坏小至导致微小的性能降级，大至整个器件故障。精密的集成电路可能更容易受到损坏，这是因为非常细微的参数更改都可能会导致器件与其发布的规格不相符。

5.6 术语表

TI 术语表	本术语表列出并解释了术语、首字母缩略词和定义。

6 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

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PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package | Pins	Package qty | Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TPS65035000RZDRQ1	Active	Production	WQFN-FCRLF (RZD) | 22	3000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	O35000
TPS65035000RZDRQ1.A	Active	Production	WQFN-FCRLF (RZD) | 22	3000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	O35000
TPS65035001RZDRQ1	Active	Production	WQFN-FCRLF (RZD) | 22	3000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	O35001
TPS65035001RZDRQ1.A	Active	Production	WQFN-FCRLF (RZD) | 22	3000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	O35001
TPS65035002RZDRQ1	Active	Production	WQFN-FCRLF (RZD) | 22	3000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	O35002
TPS65035004RZDRQ1	Active	Production	WQFN-FCRLF (RZD) | 22	3000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	O35004
TPS65035007RZDRQ1	Active	Production	WQFN-FCRLF (RZD) | 22	3000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	O35007
TPS65035007RZDRQ1.A	Active	Production	WQFN-FCRLF (RZD) | 22	3000 | LARGE T&R	Yes	NIPDAU	Level-3-260C-168 HR	-40 to 125	O35007

(1) **Status:** For more details on status, see our product life cycle.

(2) **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

(3) **RoHS values:** Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

(4) **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

(5) **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

(6) **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

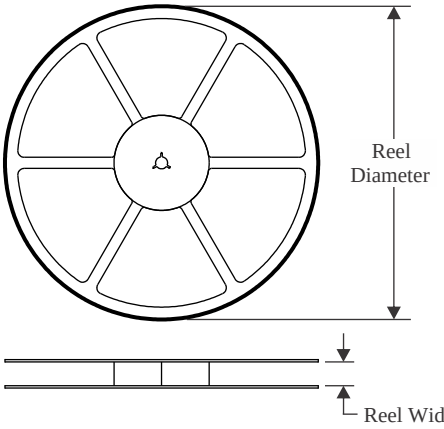
Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

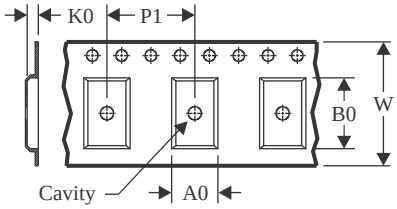
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS

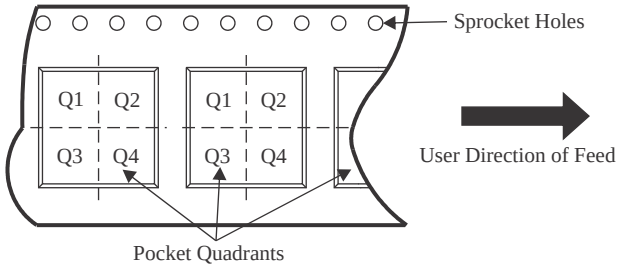


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

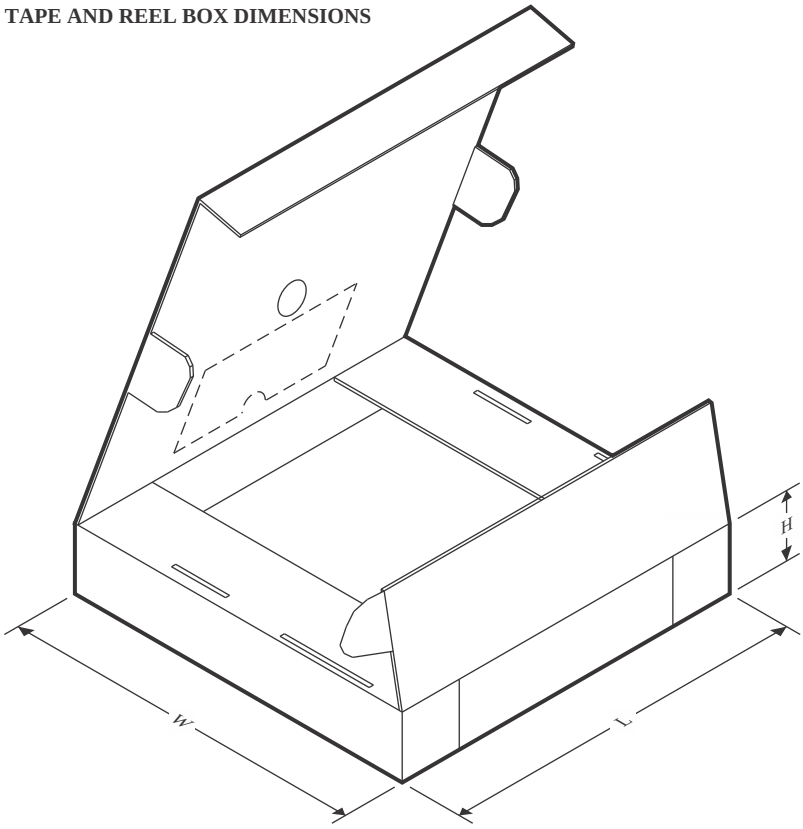
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPS65035000RZDRQ1	WQFN-FCRLF	RZD	22	3000	330.0	12.4	3.3	3.8	1.2	8.0	12.0	Q1
TPS65035001RZDRQ1	WQFN-FCRLF	RZD	22	3000	330.0	12.4	3.3	3.8	1.2	8.0	12.0	Q1
TPS65035002RZDRQ1	WQFN-FCRLF	RZD	22	3000	330.0	12.4	3.3	3.8	1.2	8.0	12.0	Q1
TPS65035004RZDRQ1	WQFN-FCRLF	RZD	22	3000	330.0	12.4	3.3	3.8	1.2	8.0	12.0	Q1
TPS65035007RZDRQ1	WQFN-FCRLF	RZD	22	3000	330.0	12.4	3.3	3.8	1.2	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

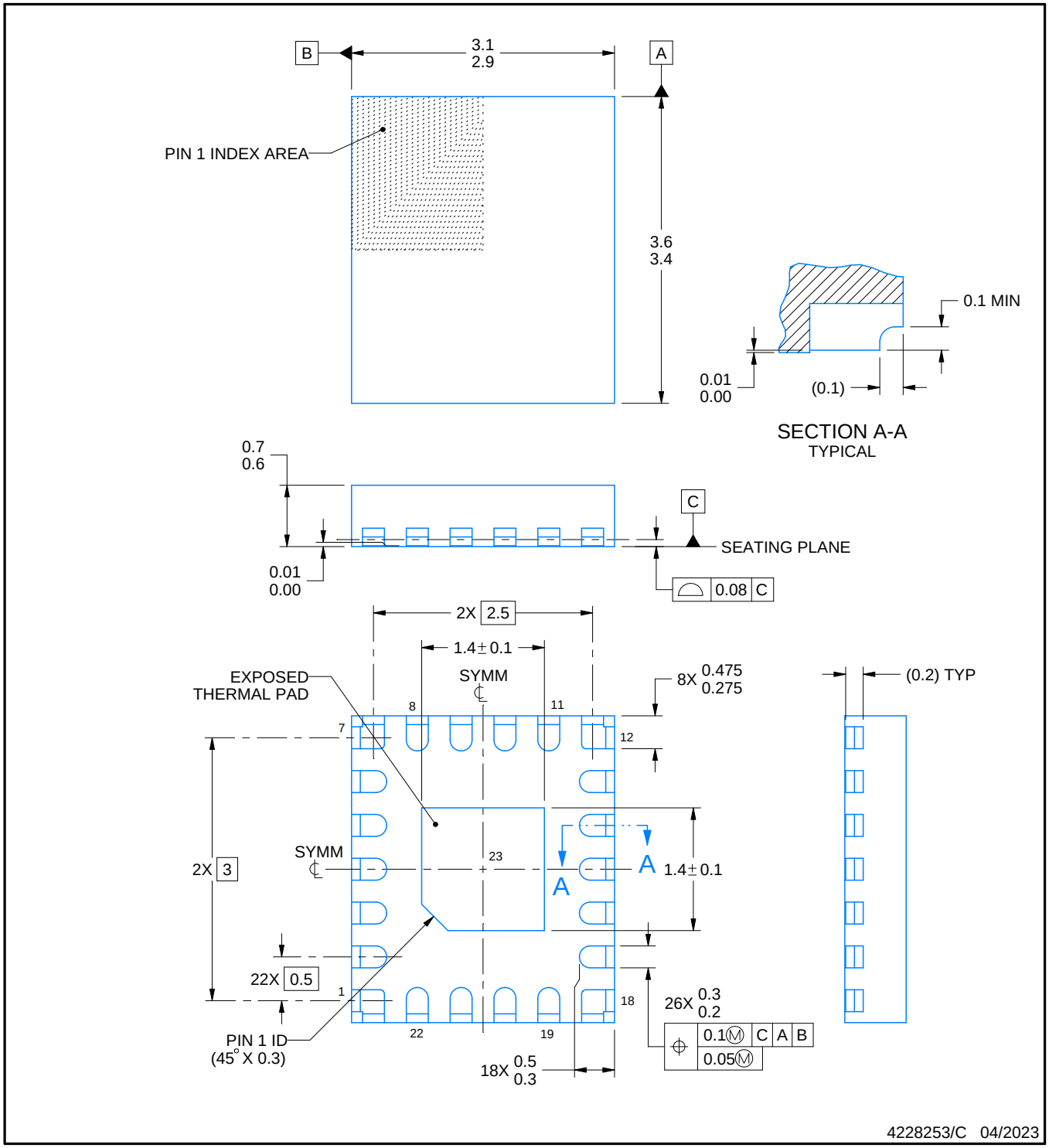
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPS65035000RZDRQ1	WQFN-FCRLF	RZD	22	3000	367.0	367.0	35.0
TPS65035001RZDRQ1	WQFN-FCRLF	RZD	22	3000	367.0	367.0	35.0
TPS65035002RZDRQ1	WQFN-FCRLF	RZD	22	3000	367.0	367.0	35.0
TPS65035004RZDRQ1	WQFN-FCRLF	RZD	22	3000	367.0	367.0	35.0
TPS65035007RZDRQ1	WQFN-FCRLF	RZD	22	3000	367.0	367.0	35.0

PACKAGE OUTLINE

RZD0022A

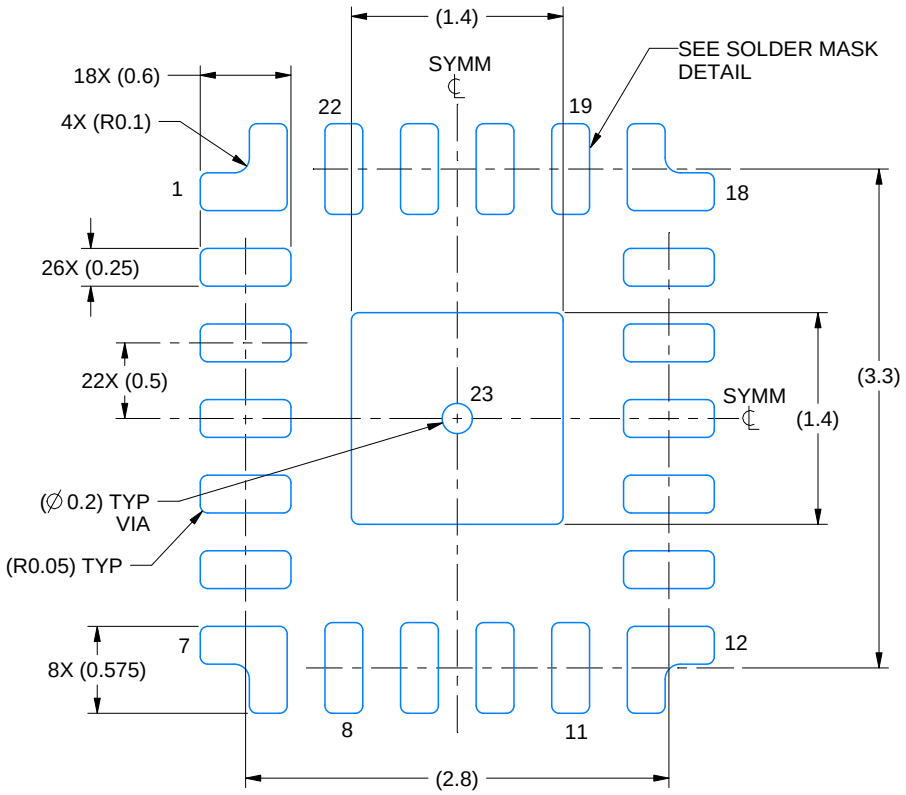
WQFN-FCRLF - 0.7 mm max height

PLASTIC QUAD FLATPACK - NO LEAD

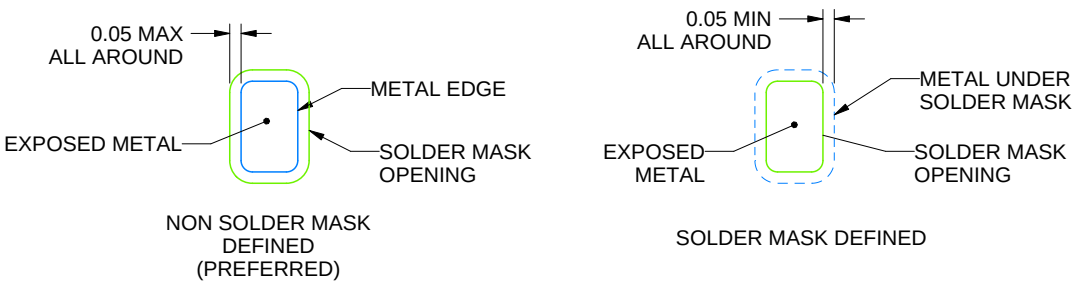


NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 20X

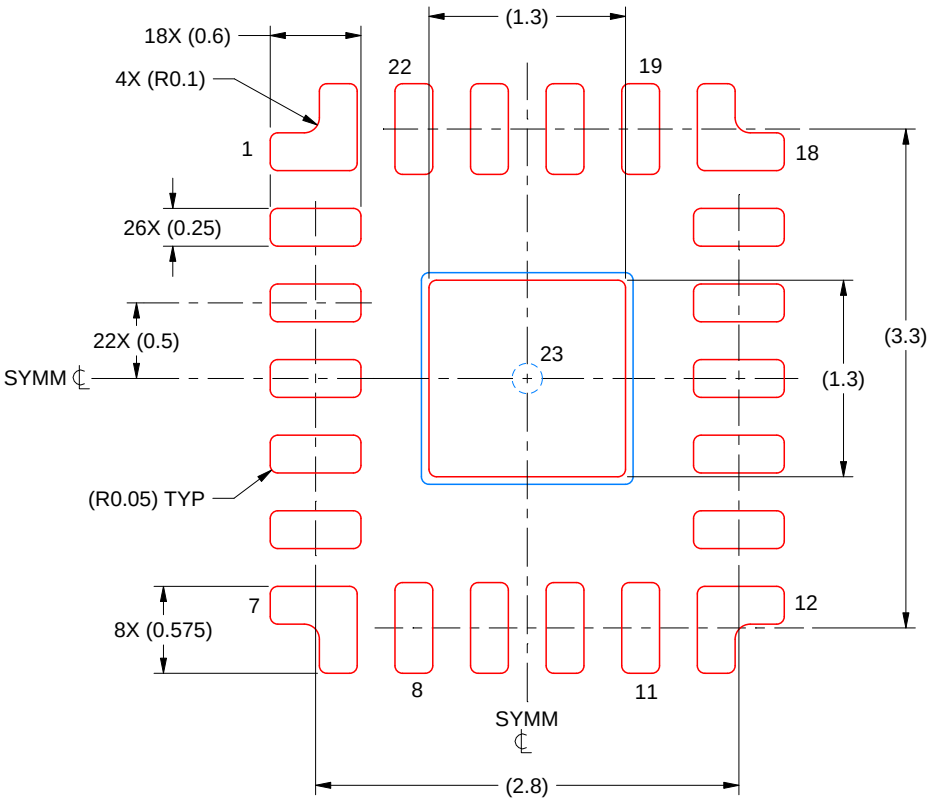


SOLDER MASK DETAILS

4228253/C 04/2023

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.



SOLDER PASTE EXAMPLE
BASED ON 0.125 MM THICK STENCIL
SCALE: 20X

EXPOSED PAD 19
86% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE

4228253/C 04/2023

NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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最后更新日期：2025 年 10 月